PC365NJ0000F **Series**

Mini-flat Package, **Darlington Phototransistor Output,** Low Input Current Photocoupler



Description

PC365NJ0000F contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat.

Low input current type.

Input-output isolation voltage(rms) is 3.75kV. CTR is MIN. 600% at input current of 0.5mA.

Features

- 1. 4-pin Mini-flat package
- 2. Double transfer mold package (Ideal for Flow Soldering)
- 3. Low input current type ($I_F=0.5mA$)
- 4. Darlington phototransistor output (CTR : MIN. 600% at $I_{F}=0.5mA$, $V_{CE}=2V$)
- 5. High isolation voltage between input and output (V_{iso(rms)}: 3.75kV)
- 6. RoHS directive compliant

Agency approvals/Compliance

- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC365)
- 2. Package resin : UL flammability grade (94V-0)

Applications

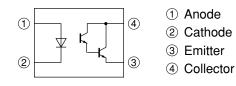
- 1. Programmable controllers
- 2. Facsimiles
- 3. Telephones

Notice The content of data sheet is subject to change without prior notice

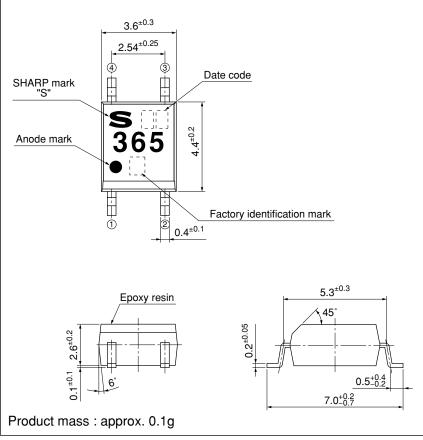
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Internal Connection Diagram



■ Outline Dimensions



Plating material : SnCu (Cu : TYP. 2%)

(Unit : mm)



Date code (2 digit)

1st digit				2nd digit		
Year of production				Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	А	2002	Р	January	1	
1991	В	2003	R	February	2	
1992	С	2004	S	March	3	
1993	D	2005	Т	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	Х	August	8	
1998	K	2010	А	September	9	
1999	L	2011	В	October	0	
2000	М	2012	С	November	N	
2001	N	:	:	December	D	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin	
no mark	Japan	
	Indonesia	
	China	

* This factory marking is for identification purpose only. Please contact the local SHARP sales representative to see the actual status of the production.

Rank mark

There is no rank mark indicator.

Absolute Maximum Ratings

			-	(-a)
Parameter		Symbol	Rating	Unit
	Forward current	I_F	10	mA
Input	*1 Peak forward current	I_{FM}	200	mA
Ing	Reverse voltage	V _R	6	V
	Power dissipation	Р	15	mW
Collector-emitter voltage		V _{CEO}	35	V
Output	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	80	mA
	Collector power dissipation	P _C	150	mW
Total power dissipation		P _{tot}	170	mW
*2 Isolation voltage		V _{iso (rms)}	3.75	kV
Operating temperature		T _{opr}	-30 to +100	°C
Storage temperature		T _{stg}	-40 to +125	°C
*3 Soldering temperature		T _{sol}	260	°C

*1 Pulse width≤100µs, Duty ratio : 0.001

*2 40 to 60%RH, AC for 1 minute, f=60Hz

*3 For 10s

Electro-optical Characteristics

 $(T_a=25^{\circ}C)$ Parameter Symbol Conditions MIN. TYP. MAX. Unit Forward voltage VF I_F=5mA 1.2 1.4 V _ Reverse current $V_R=4V$ 10 μΑ Input I_R _ _ \mathbf{C}_{t} V=0, f=1kHz pF Terminal capacitance 30 250 - $V_{CE}=10V, I_{F}=0$ Collector dark current I_{CEO} _ _ 1000 nA Output Collector-emitter breakdown voltage BV_{CEO} $I_{C}=0.1 \text{mA}, I_{F}=0$ 35 V _ _ v Emitter-collector breakdown voltage BV_{ECO} $I_E = 10 \mu A$, $I_F = 0$ 6 _ _ 3 Collector current $I_{\rm C}$ $I_F=0.5mA$, $V_{CE}=2V$ 14 60 mА Collector-emitter saturation voltage V_{CE (sat)} $I_F=1mA$, $I_C=2mA$ 1.0 V _ _ Transfer 5×10^{10} Isolation resistance DC500V, 40 to 60%RH 1×10^{11} Ω R_{ISO} _ charac-Floating capacitance V=0, f=1MHz 0.6 1.0 C_{f} pF teristics Rise time $\mathbf{t}_{\mathbf{r}}$ _ 60 300 μs $V_{CE}=2V, I_{C}=10mA, R_{L}=100\Omega$ Response time Fall time 53 250 $t_{\rm f}$ _ μs

 $(T_a=25^{\circ}C)$

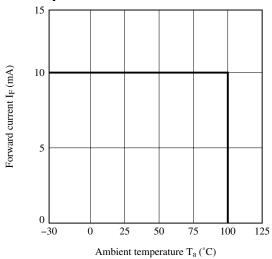


■ Model Line-up

Dealeaga	Taping			
Package	3 000 pcs/reel	750 pcs/reel		
Model No.	PC365NJ0000F	PC365NTJ000F		

Please contact a local SHARP sales representative to inquire about production status.

Fig.1 Forward Current vs. Ambient Temperature





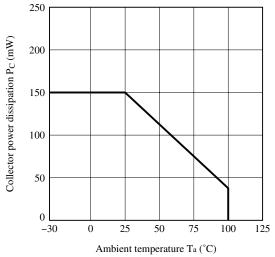


Fig.5 Peak Forward Current vs. Duty Ratio

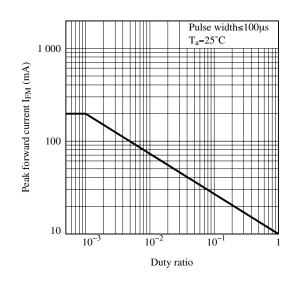


Fig.2 Diode Power Dissipation vs. Ambient Temperature

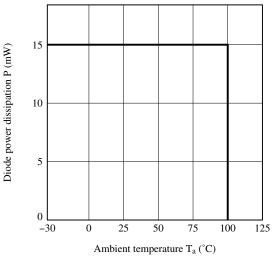


Fig.4 Total Power Dissipation vs. Ambient Temperature

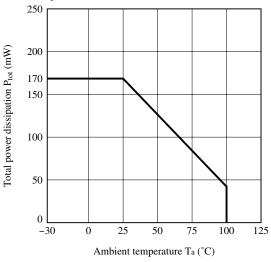
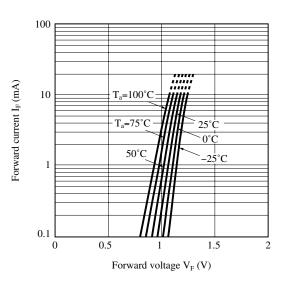
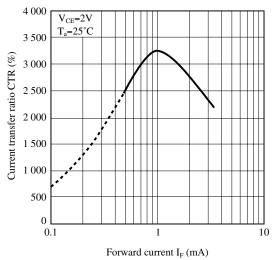


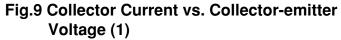
Fig.6 Forward Current vs. Forward Voltage

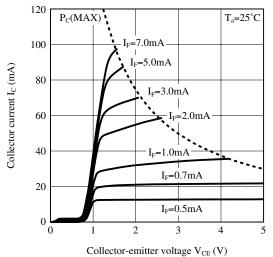




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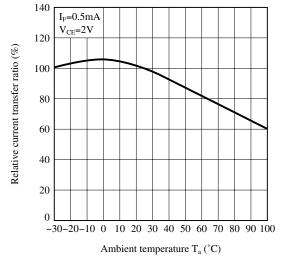
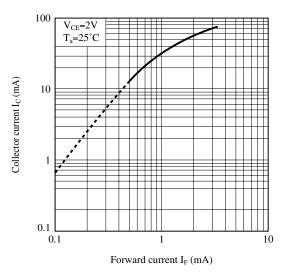
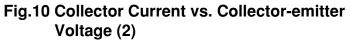


Fig.8 Collector Current vs. Forward Current





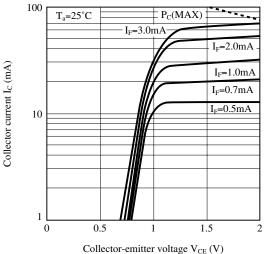


Fig.12 Collector - emitter Saturation Voltage vs. Ambient Temperature

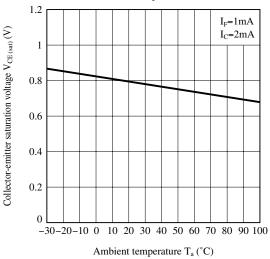


Fig.13 Collector Dark Current vs. Ambient Temperature

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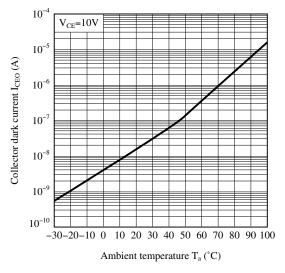
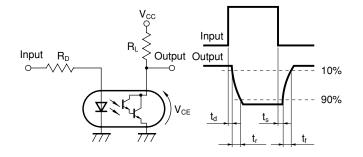


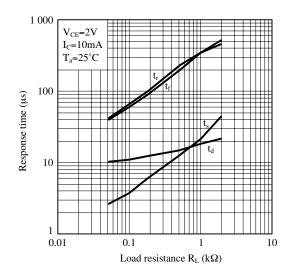
Fig.15 Test Circuit for Response Time



Please refer to the conditions in Fig.14

Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

Fig.14 Response Time vs. Load Resistance





Design Considerations

Design guide

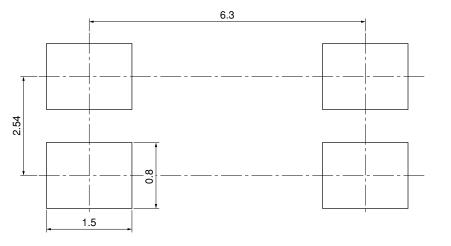
While operating at I_{F} <0.5mA, CTR variation may increase. Please make design considering this fact.

This product is not designed against irradiation and incorporates non-coherent IRED.

Degradation

In general, the emission of the IRED used in photocouplers will degrade over time. In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

• Recommended Foot Print (reference)



☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

(Unit : mm)

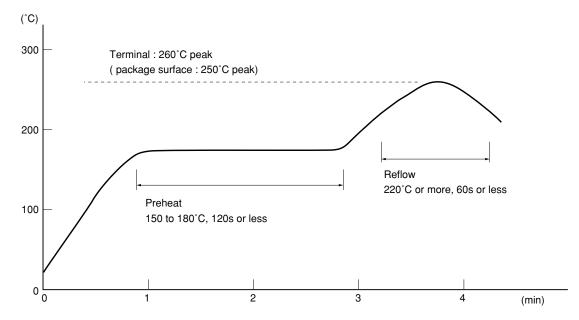


Manufacturing Guidelines

Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



• Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3 minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials. And they are not used in the production process for this product. Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).
•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



■ Package specification

• Tape and Reel package

1. 3 000pcs/reel

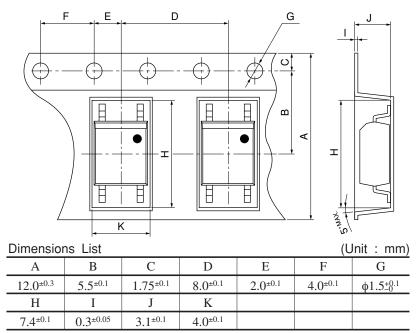
Package materials

Carrier tape : A-PET (with anti-static material)

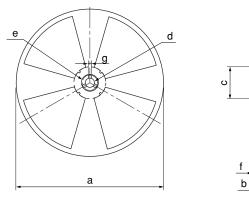
Cover tape : PET (three layer system)

Reel : PS

Carrier tape structure and Dimensions

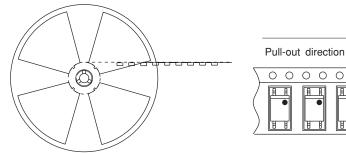


Reel structure and Dimensions



Dimensio	ns List	(Unit : mm)		
а	a b		d	
370	13.5 ^{±1.5}	80 ^{±1.0}	13 ^{±0.5}	
e	f	g		
21 ^{±1.0}	$2.0^{\pm 0.5}$	2.0 ^{±0.5}		

Direction of product insertion



[Packing: 3 000pcs/reel]



2.750pcs/reel

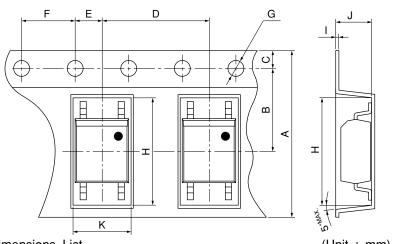
Package materials

Carrier tape : A-PET (with anti-static material)

Cover tape : PET (three layer system)

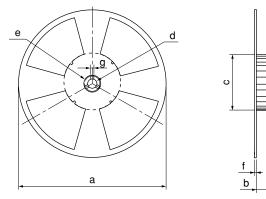
Reel : PS

Carrier tape structure and Dimensions



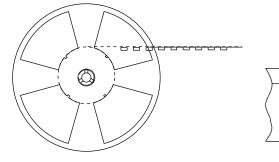
Dimensions List (Unit : mm						
А	В	C	D	Е	F	G
12.0 ^{±0.3}	$5.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$8.0^{\pm 0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 ^{+0.1}
Н	Ι	J	K			
$7.4^{\pm 0.1}$	$0.3^{\pm 0.05}$	$3.1^{\pm 0.1}$	$4.0^{\pm 0.1}$			

Reel structure and Dimensions



Dimensio	ns List	(Unit : mm)		
а	b	с	d	
180	13.5 ^{±1.5}	80 ^{±1.0}	13 ^{±0.5}	
e	f	g		
21 ^{±1.0}	$2.0^{\pm 0.5}$	2.0 ^{±0.5}		

Direction of product insertion



[Packing : 750pcs/reel]

Pull-out direction

A A

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A A

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment [terminal]
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment [trunk lines]
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g., scuba).

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